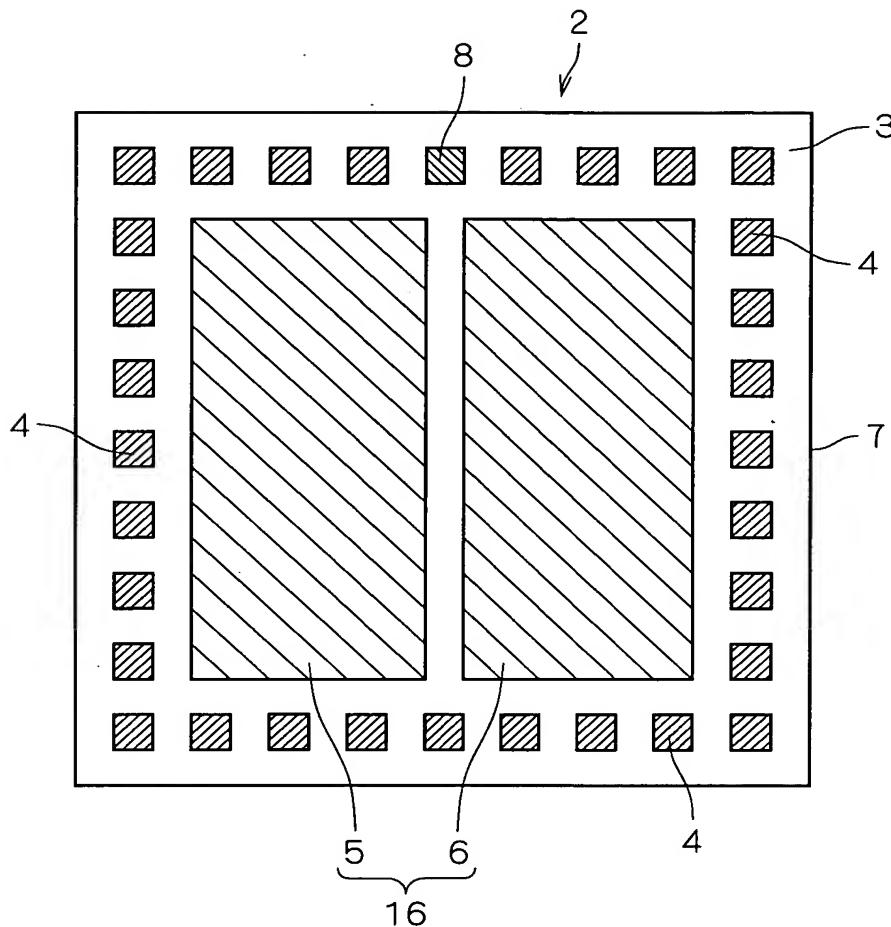


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FIG. 1

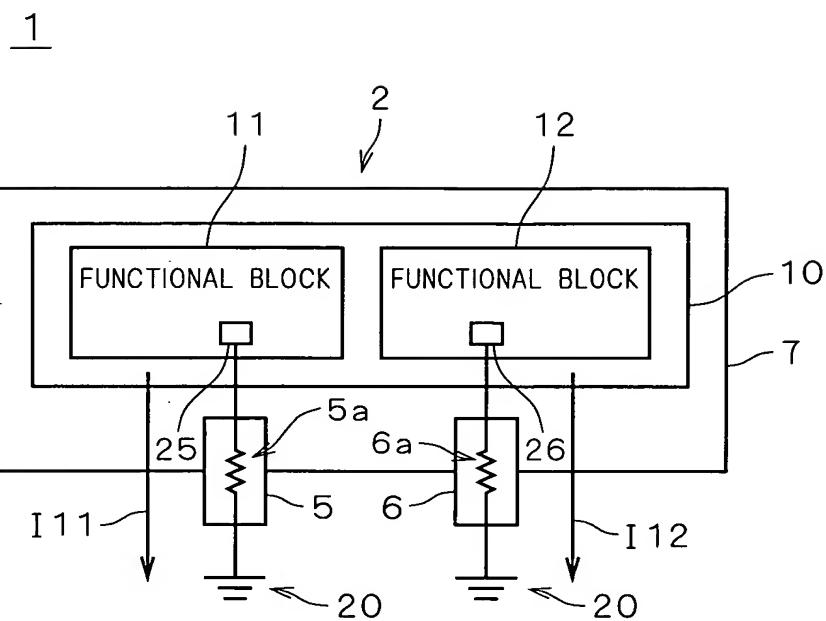
1

- 1: SEMICONDUCTOR DEVICE
- 2: PACKAGE
- 3: MOLDING RESIN
- 4: SIGNAL TERMINALS
- 5, 6, 16: GROUND TERMINALS

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FIG. 2



10: SEMICONDUCTOR INTEGRATED CIRCUIT

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FIG. 3

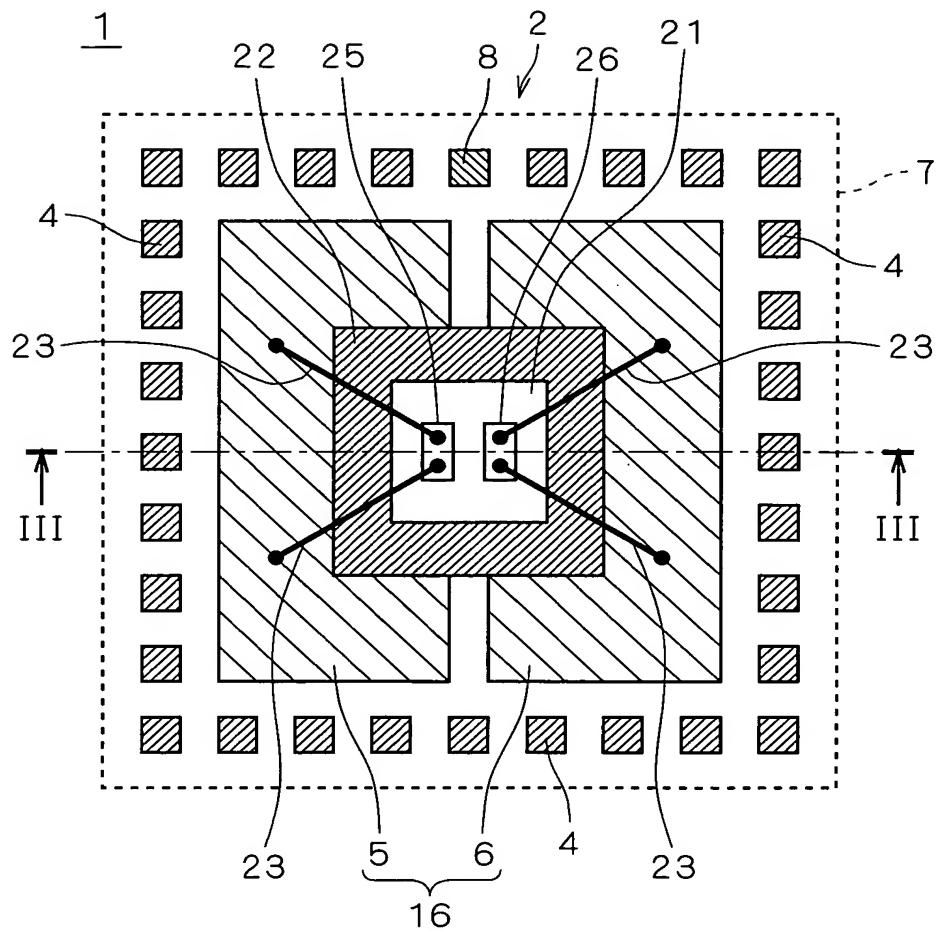
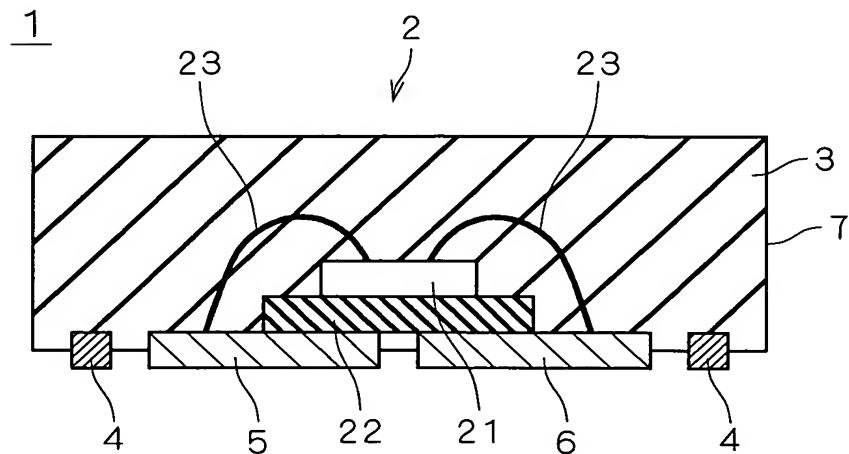


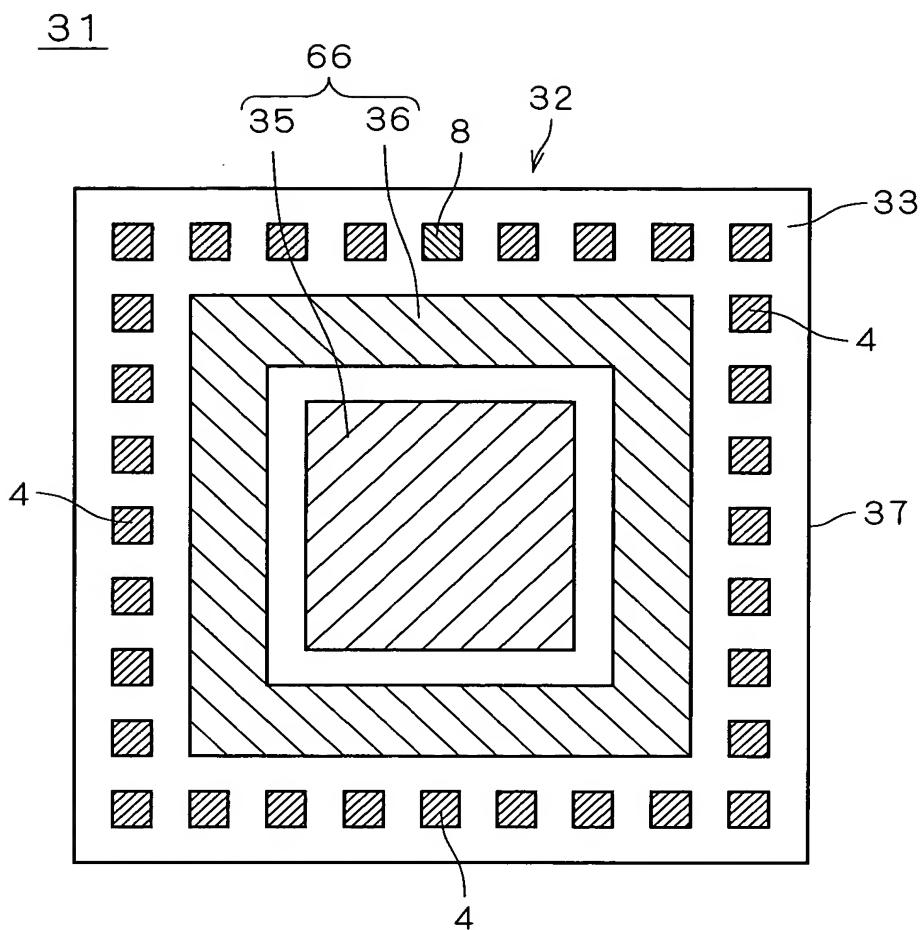
FIG. 4



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FIG. 5



31: SEMICONDUCTOR DEVICE  
32: PACKAGE  
33: MOLDING RESIN  
35, 36, 66: GROUND TERMINALS

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FIG. 6

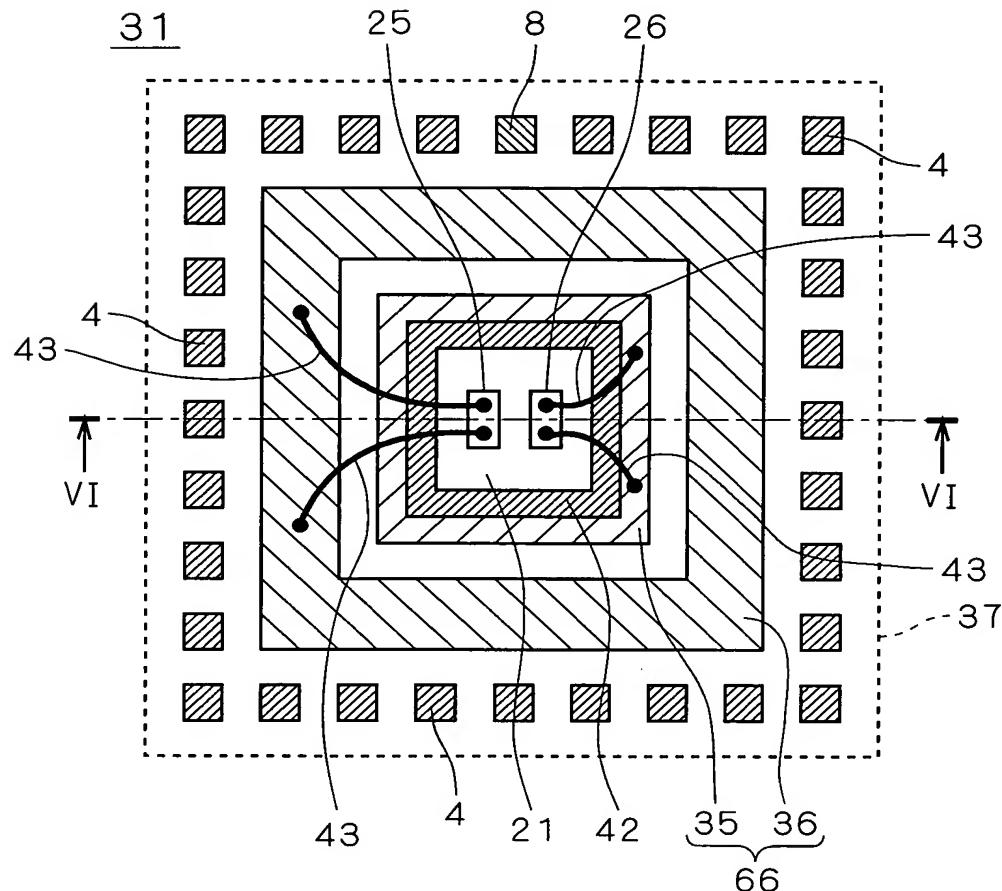
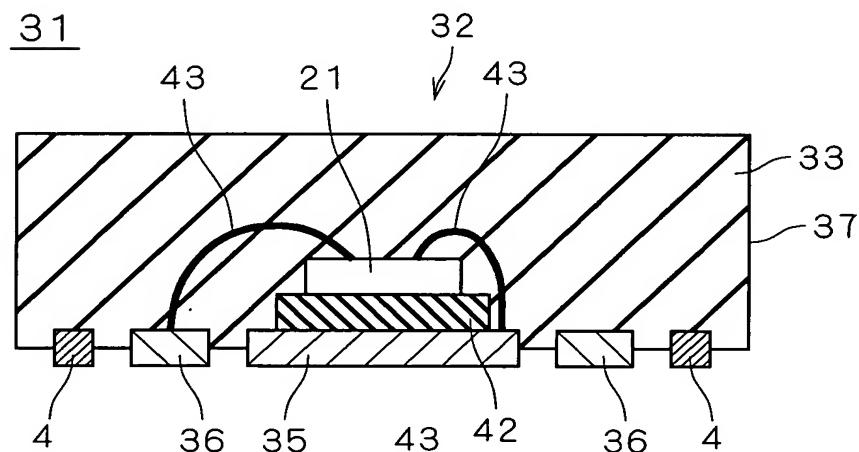


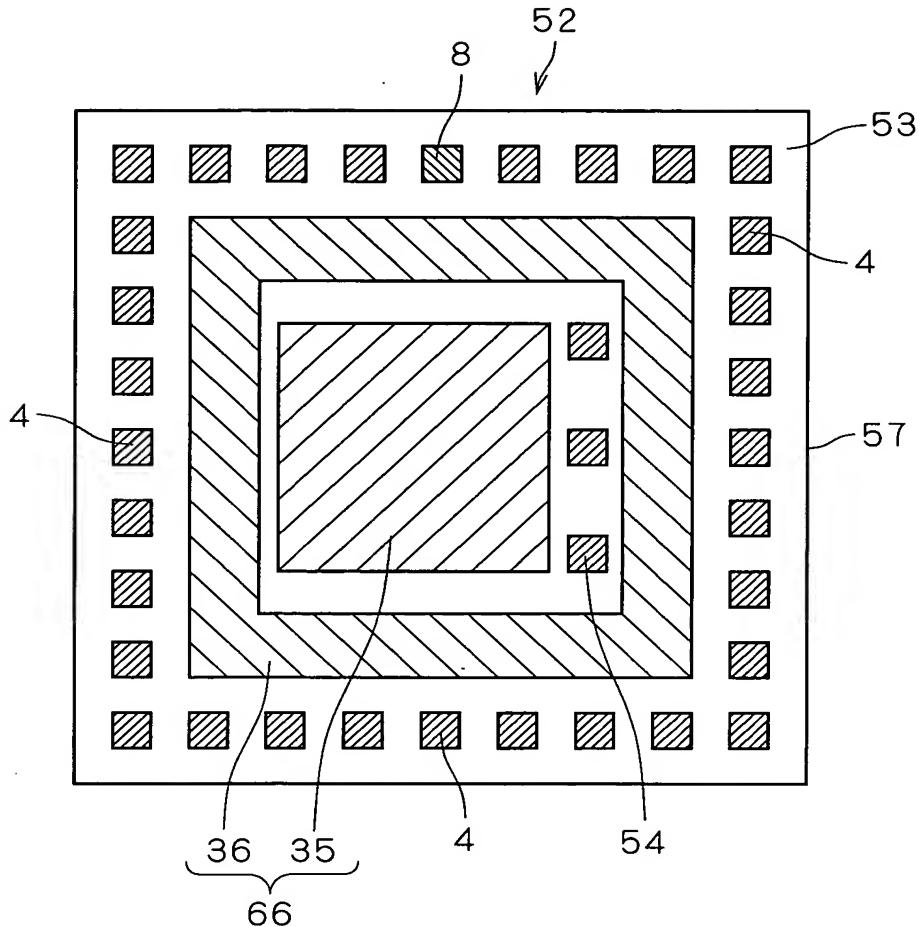
FIG. 7



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51

51: SEMICONDUCTOR DEVICE  
52: PACKAGE  
53: MOLDING RESIN  
54: SIGNAL TERMINALS

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FIG. 9

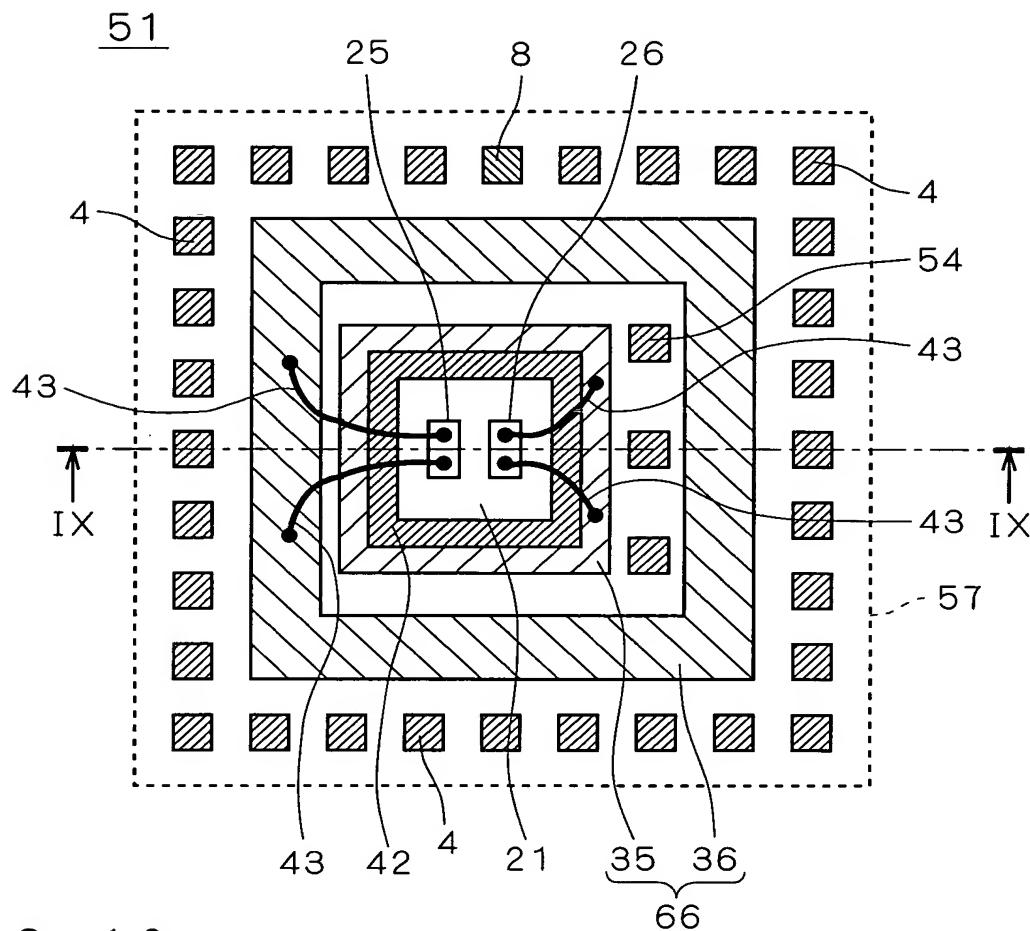
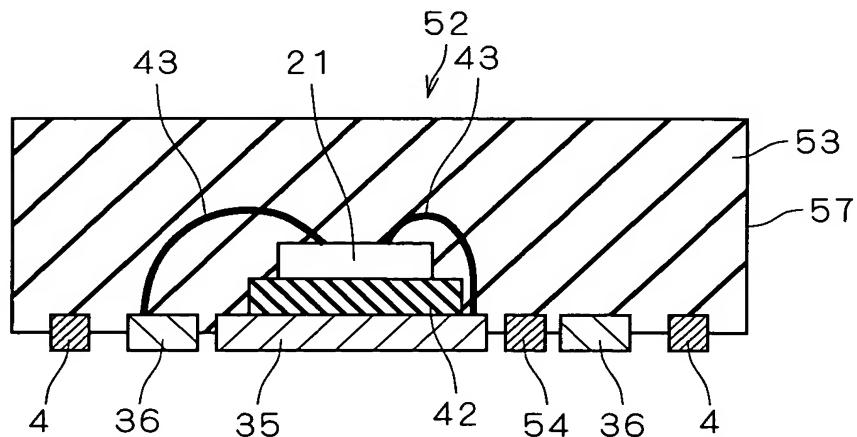


FIG. 10



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FIG. 11

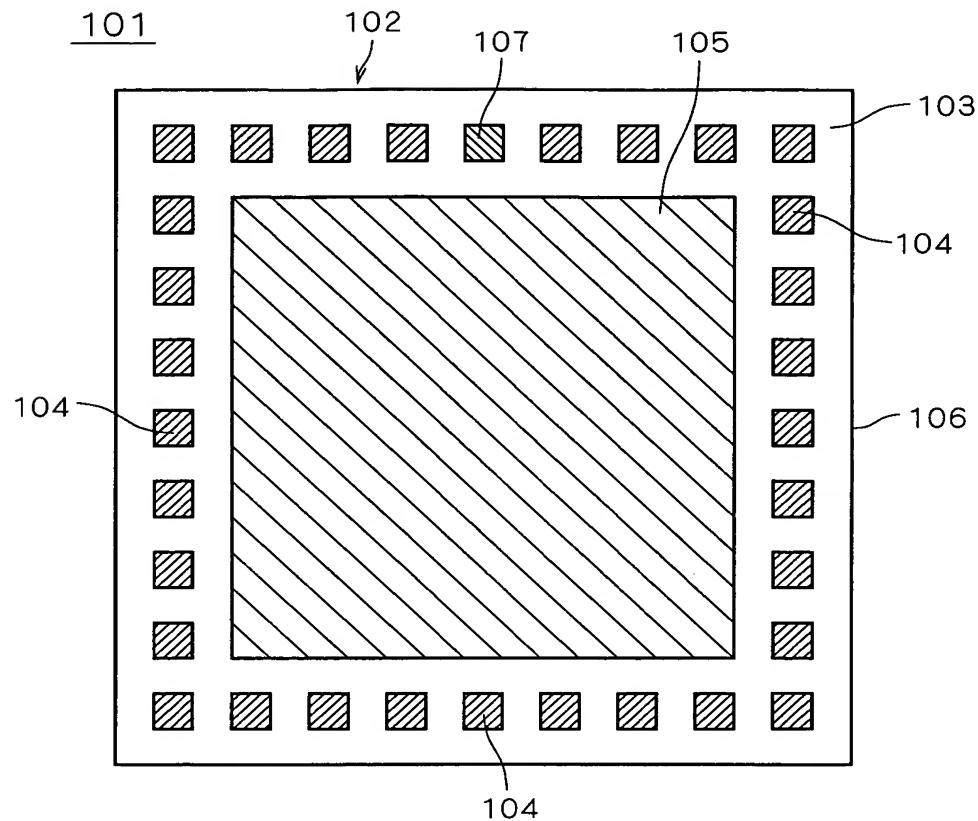


FIG. 12

